



Major Ratings and Characteristics

$I_{F(AV)}$	3A
V_{RRM}	20V to 100V
I_{FSM}	100A
I_R	500uA
V_F	0.55V, 0.7V, 0.85V
T_{jMAX}	150°C

Features

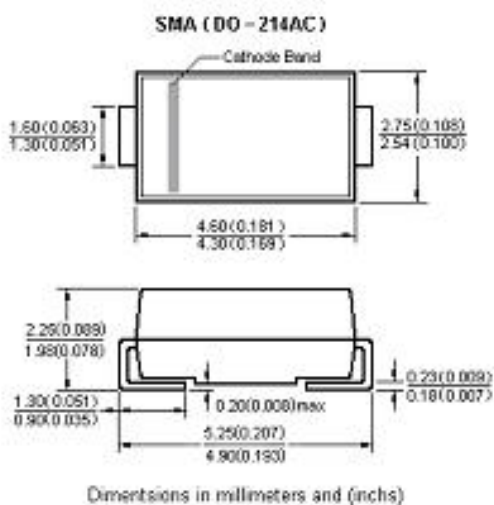
- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Data

- Case: JEDEC DO-214AC molded plastic body over passivated chip
- Terminals: Solder plated, solderable per J-STD-002B and JESD22-B102D
- Polarity: Laser band denotes cathode end

Maximum Ratings & Thermal Characteristics & Electrical Characteristics

(TA = 25 °C unless otherwise noted)



Type Number	SYMBOL	SS32	SS33	SS34	SS35	SS36	SS38	SS310	unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	20	30	40	50	60	80	100	V
Maximum RMS Voltage	V_{RMS}	14	21	28	35	42	56	70	V
Maximum DC blocking Voltage	V_{DC}	20	30	40	50	60	80	100	V
Maximum Average Forward Rectified Current .at TA =55°C	$I_{F(AV)}$	3							A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	100							A
Maximum Forward Voltage at 1.5A DC	V_F	0.55			0.70		0.85		V
Maximum DC Reverse Current @TA =25°C	I_R	0.5							mA
At rated DC blocking voltage @TA=100°C		40							
Typical Junction Capacitance (Note1)	C_j	300							pF
Typical Thermal Resistance (Note 2)	$R_{(JA)}$	85							°C /W
Storage Temperature	T_{STG}	-55 to +150							°C
Operation Junction Temperature	T_J	-55 to +125							°C



RATING AND CHARACTERISTIC CURVES

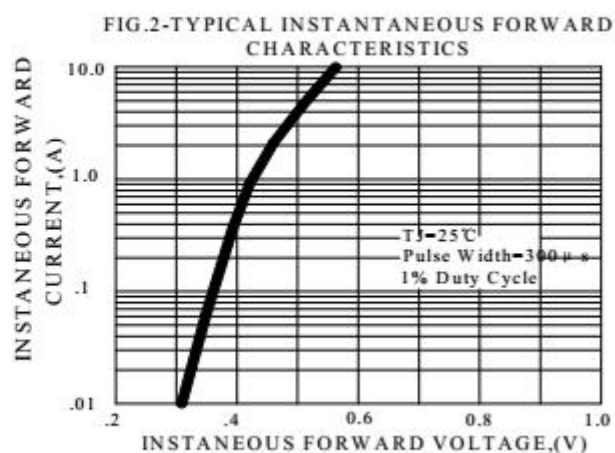
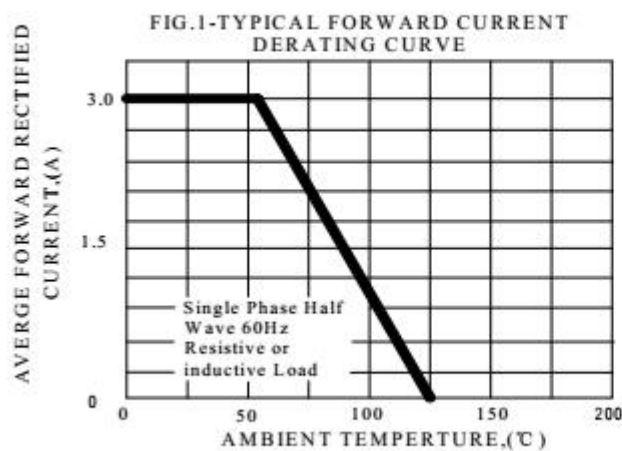


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

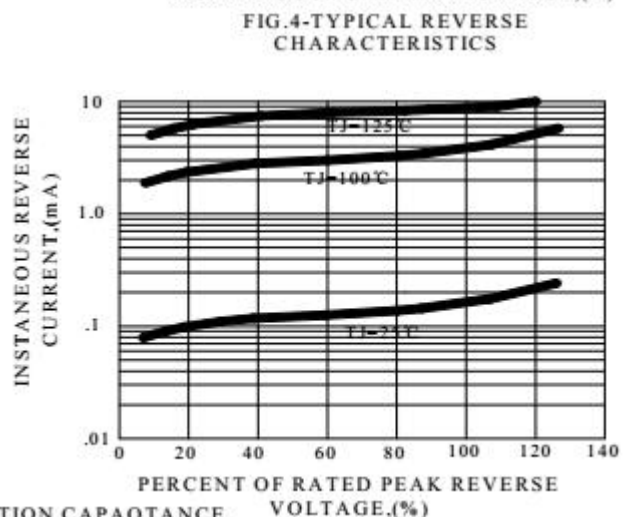
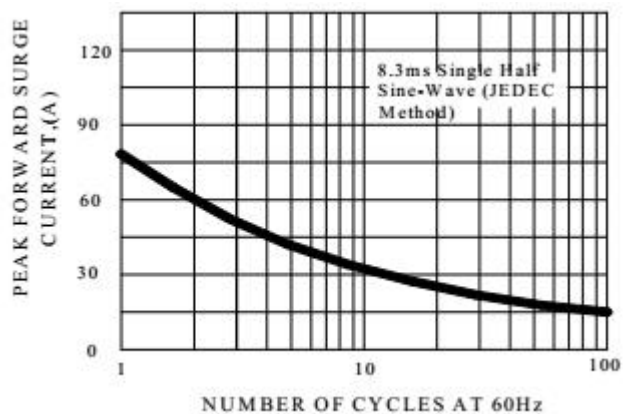


FIG.5-TYPICAL JUNCTION CAPACITANCE

